



## Material Content Data Sheet



<b>Sales Product Name</b>		2EDL05I06BF		<b>Issued</b>		20. May 2016			
<b>MA#</b>		MA001371650							
<b>Package</b>		PG-DSO-8-53		<b>Weight*</b>		80.26 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.952	1.19	1.19	11864	11864	
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		105		
	non noble metal	zinc	7440-66-6	0.034	0.04		419		
	non noble metal	iron	7439-89-6	0.673	0.84		8387		
wire	non noble metal	copper	7440-50-8	27.330	34.05	34.94	340529	349440	
	noble metal	gold	7440-57-5	0.185	0.23	0.23	2305	2305	
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1237	
encapsulation	plastics	epoxy resin	-	5.359	6.68		66771		
	inorganic material	silicondioxide	60676-86-0	44.162	55.02	61.82	550246	618254	
leadfinish	non noble metal	tin	7440-31-5	0.824	1.03	1.03	10267	10267	
plating	noble metal	silver	7440-22-4	0.090	0.11	0.11	1116	1116	
glue	plastics	acrylic resin	-	0.119	0.15		1486		
	noble metal	silver	7440-22-4	0.423	0.53	0.68	5268	6754	
*deviation	< 10%				Sum in total:		100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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